

TITLE

PROCESS FOR REMOVING AN ORGANIC LAYER DURING  
FABRICATION OF AN ORGANIC ELECTRONIC DEVICE AND THE  
ORGANIC ELECTRONIC DEVICE FORMED BY THE PROCESS

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ABSTRACT OF THE DISCLOSURE

A method of dry etching a performance sensitive element of an organic electronic device, said method comprising the steps of: (a) having at least one performance sensitive element on the substrate spaced apart from a first conductive member, wherein at least one of the performance 10 sensitive elements is a conductive lead; (b) placing organic material on the performance sensitive element and the first conductive member; (c) forming a patterned conductive layer over the organic material exposing a predetermined portion of the performance sensitive elements; and (d) dry etching the organic material in the exposed areas of the 15 performance sensitive elements using at least one oxygen-containing gas, and organic electronic device created using said process.

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35 MAC/dmm